International Application No.: PCT/JP2004/015621

U.S. Patent Application No.: Unknown

May 24, 2006 Page 2 of 10

AMENDMENTS TO THE SPECIFICATION:

A substitute specification and a marked-up copy of the English translation of the originally filed PCT application are attached hereto.

Please replace the Title of the Invention originally filed with the above-identified patent application with the following <u>new</u> Title:

METHOD FOR FORMING THICK FILM PATTERN, METHOD FOR
MANUFACTURING ELECTRONIC COMPONENT, AND PHOTOLITHOGRAPHY
PHOTOSENSITIVE PASTE